

Docket No. 0756-2413

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT application of)
Yasuhiko TAKEMURA et al.)
Serial No. 10/028,269) Confirmation No. 2821
Filed: December 28, 2001)
For: SEMICONDUCTOR DEVICE AND)
A MANUFACTURING METHOD FOR)
THE SAME)

CERTIFICATE OF MAILING

I hereby certify that the correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on 5-6-02
Rose M. Siegel

PRELIMINARY AMENDMENT

Please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 1 in its entirety.

Please add new claims 2-21 as follows:

2. A method for forming a semiconductor device comprising:
forming a semiconductor film over a substrate;
forming a first insulating film comprising silicon oxide over said semiconductor film;
forming a gate electrode over said first insulating film;
 patterning said first insulating film into a second insulating film comprising silicon oxide;
introducing an impurity into said semiconductor film using said gate electrode and said second insulating film as masks to form a source region and a drain



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FACSIMILE COVER SHEET

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RE: Application Serial No. 10/028,269
Our Reference: 0756-2413

As requested.

Eric J. Robinson